PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SHARAD SAXENA	09/01/2015
TOMASZ BROZEK	09/02/2015
YUAN YU	09/04/2015
MIKE KYU HYON PAK	08/31/2015
MEINDERT MARTIN LUNENBORG	09/01/2015

RECEIVING PARTY DATA

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Street Address:	333 WEST SAN CARLOS STREET
Internal Address:	SUITE 1000
City:	SAN JOSE
State/Country:	CALIFORNIA
Postal Code:	95110

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14839674

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	63207-0439861/PDFS-0097U1
NAME OF SUBMITTER:	DAVID A. JAKOPIN
SIGNATURE:	/DAVID A. JAKOPIN/
DATE SIGNED:	10/26/2015
	This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 5
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source=PDFS0097u1_Assignment_Oaths#page2.tif
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source=PDFS0097u1_Assignment_Oaths#page4.tif
source=PDFS0097u1_Assignment_Oaths#page5.tif

Combined Inventor's Declaration, Assignment, and Designation of PDF Solutions, Inc. as Applicant for Patent

Inventorship

I, as the undersigned inventor or one of the undersigned joint inventors, hereby declare as follows with respect to U.S. Patent Application Docket No. PDFS-0097-u1, entitled "Test Structures And Methods For Measuring Silicon Thickness In Fully Depleted Silicon-On-Insulator Technologies," filed August 28, 2015 (hereafter referred to as "the application" or "the above-identified application"):

1. The above-identified application was made or authorized to be made by me.
2. I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Assignment of Rights

Pursuant to legal obligation, and for good and valuable consideration, both of which are hereby acknowledged, I **hereby assign and/or acknowledge my previous assignment of** all of my right, title, and interest in the application and any invention or patent application for any invention disclosed therein, as well as any non-provisional, continuation, divisional, continuation-in-part, reexamination, reissue, extension, or foreign counterpart of any of the foregoing, to **PDF Solutions, Inc., a Delaware corporation, having a principal place of business in San Jose, California** (hereafter, "PDF").

Designation of PDF as Applicant

I hereby acknowledge that the foregoing assignment will enable PDF to file and prosecute patent applications, as the applicant, for any of the assigned applications/inventions. I consent to PDF's use of my name as inventor or joint inventor on patents and patent applications covered by the assignment herein, and I hereby designate PDF as my attorney-in-fact with respect to any such patents or patent applications.

Sharad Saxena

Sharad SAXENA — 09/01/2015 Date

Tomasz BROZEK — Date

Yuan YU — Date

Mike Kyu Hyon PAK — Date

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Sharad SAXENA	Date
Tomasz BROZEK	Sept - 02, 2015 Date
Yuan YU	Date
Mike Kyu Hyon PAK	Date
Meindert Martin LUNENBORG	Date

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